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捷多邦,专业PCB打样工厂,24小时加急 Pamgsonic

#### Transistor

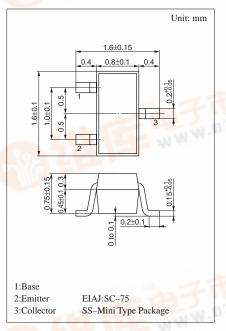
# 2SD2240, 2SD2240A

Silicon NPN epitaxial planer type

For high breakdown voltage low-frequency and low-noise amplification

- Features
- High collector to emitter voltage V<sub>CEO</sub>.
- Low noise voltage NV.
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing.

Absolute Maximum Ratings (Ta=25°C)								
Parameter		Symbol	Ratings	Unit				
Collector to	2SD2240	V	150	V				
base voltage	2SD2240A	V <sub>CBO</sub>	185	v				
Collector to	2SD2240	V	150	V				
emitter voltage	2SD2240A V <sub>CEO</sub>		185	v				
Emitter to base voltage		$V_{EBO}$	5	V				
Peak collector current		I <sub>CP</sub>	100	mA				
Collector current		I <sub>C</sub>	50	mA				
Collector power dissipation		P <sub>C</sub>	125	mW				
Junction temperature		Tj	125	°C				
Storage temperature		T <sub>stg</sub>	-55 ~ +125	°C				
			A REAL PROPERTY OF					



Marking symbol : P(2SD2240) L(2SD2240A)

#### Electrical Characteristics (Ta=25°C)

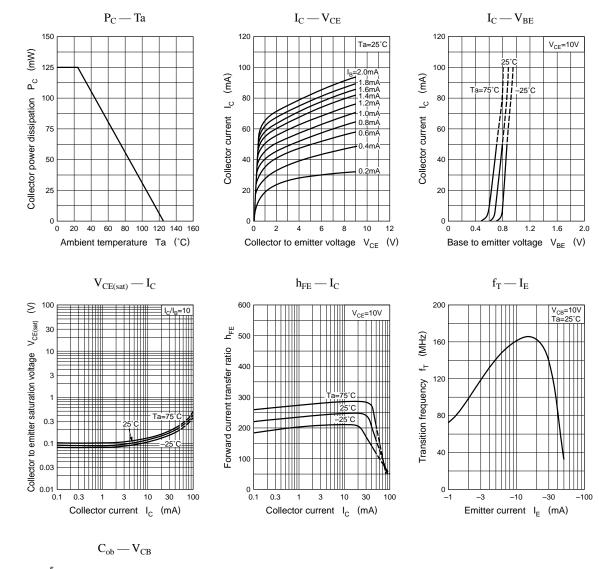
Parameter		Symbol	Conditions	min	typ	max	Unit
Collector cutoff current		I <sub>CBO</sub>	$V_{CB} = 100V, I_E = 0$			1	μΑ
Collector to emitter	2SD2240	17	$I_{C} = 100 \mu A, I_{B} = 0$	150		2 65	v
voltage	2SD2240A	V <sub>CEO</sub>		185		14 M	
Emitter to base voltage		V <sub>EBO</sub>	$I_{\rm E} = 10 \mu A, I_{\rm C} = 0$	5			V
Forward current transfer ratio		h <sub>FE</sub> *	$V_{CE} = 5V, I_{C} = 10mA$	130		330	
Collector to emitter saturation voltage		V <sub>CE(sat)</sub>	$I_{\rm C} = 30 {\rm mA}, I_{\rm B} = 3 {\rm mA}$			1	V
Transition frequency		f <sub>T</sub>	$V_{CB} = 10V, I_E = -10mA, f = 200MHz$		150		MHz
Collector output capacitance		C <sub>ob</sub>	$V_{CB} = 10V, I_E = 0, f = 1MHz$		2.3		pF
Noise voltage		NV	$V_{CE} = 10V, I_C = 1mA, G_V = 80dB$ $R_g = 100k\Omega$ , Function = FLAT		150		mV

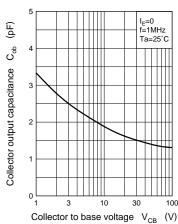
<sup>\*1</sup>h<sub>FE1</sub> Rank classification



## Transistor

# 2SD2240, 2SD2240A





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